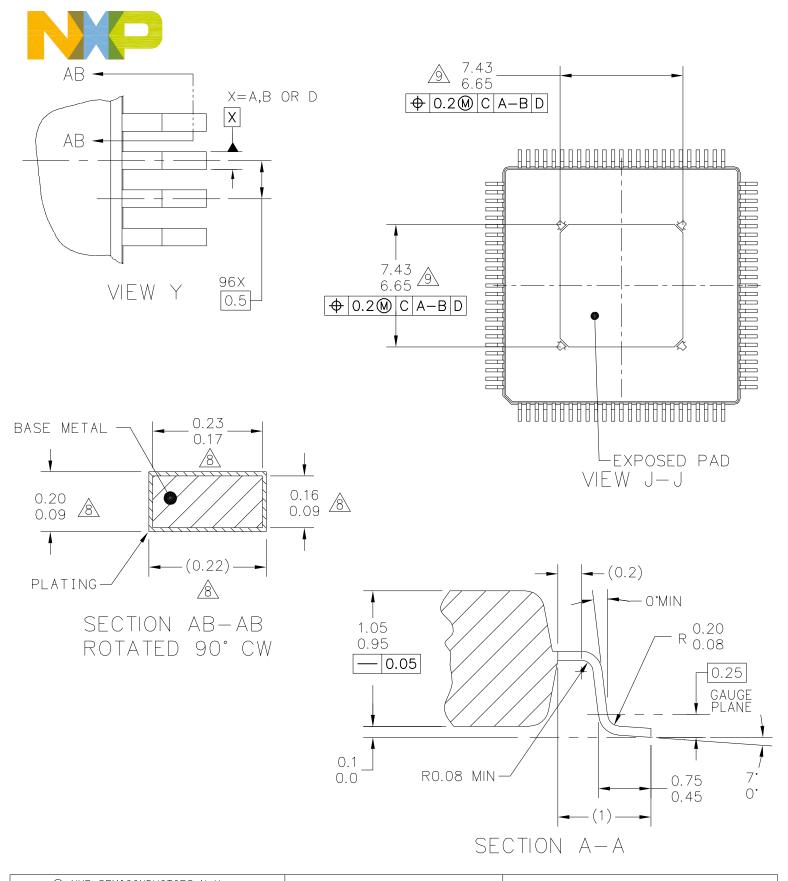


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TITLE: 100LD TQFP,			DOCUMENT NO: 98ARH99118A REV: H		
14 X 14 X 1.0 PKG, 0.5 PITCH, 7.0X7.0 EXPOSED PAD		STANDARD: JEDEC MS-026 AED-HD			
		S0T638-	-7 25 DEC 2015		



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14 X 14 X 1.0 PKG,		DOCUMEN	NT NO: 98ARH99118A	REV: H
		STANDARD: JEDEC MS-026 AED-HD		
0.5 PITCH, 7.0X7.0 EXP	DSED PAD	S0T638-	-7 25	5 DEC 2015



NOTES:

- 1. DIMENSIONS ARE IN MILLIMETERS.
- 2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.
- 3. DATUMS A, B AND D TO BE DETERMINED AT DATUM PLANE H.
- DIMENSIONS TO BE DETERMINED AT SEATING PLANE C
- THIS DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED THE UPPER LIMIT BY MORE THAN 0.08 MM. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSION AND ADJACENT LEAD OR PROTRUSION 0.07 MM.
- THIS DIMENSION DOES NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25 MM PER SIDE. THIS DIMENSION IS MAXIMUM PLASTIC BODY SIZE DIMENSIONS INCLUDING MOLD MISMATCH.
- EXACT SHAPE OF EACH CORNER IS OPTIONAL.
- THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10 mm AND 0.25 MM FROM THE LEAD TIP.
- SOLDERABLE AREA WITHIN THE INNER GROOVE OF THE PACKAGE IS GUARANTEED TO BE 5.7X5.7MM.SQ. THE PACKAGE MAXIMUM EXPOSED PAD AREA IS 7.43X7.43MM.SQ WHICH INCLUDES THE DOUBLE GROOVES.
- 10. LEADFRAME PART NUMBER APPLIED IS 17ASS23306W706/681.

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TITLE: 100LD TQFP, 14 X 14 X 1.0 PKG, 0.5 PITCH, 7.0X7.0 EXPOSED PAD		DOCUMENT NO: 98ARH99118A REV: H			
		STANDARD: JEDEC MS-026 AED-HD			
		S0T638-	25 DEC 2015		